

**AMENDMENTS TO THE CLAIMS:**

This listing of claims will replace all prior versions, and listings, of claims in the application.

**Listing of Claims:**

1.-13. (Canceled).

14. (Currently Amended) A method of fabricating a magnetic head cluster comprising the steps of:

providing a substrate;

forming a plurality of transducer elements positioned between a first edge of the substrate and a second edge of the substrate, the second edge opposing the first edge at least two transducer elements on a surface of the substrate; and

forming at least one resistive element on the surface of the substrate between two of the at least two transducer elements, wherein the plurality of transducer elements includes a first transducer and a last transducer, the first transducer having no resistive elements positioned between the first transducer and the first edge and the last transducer having no resistive elements positioned between the last transducer and the second edge;

placing at least one surface of the substrate against a lapping plate or diamond lapping film;

applying pressure to the substrate in a direction substantially perpendicular to the lapping plate or diamond lapping film; and

lapping the substrate by placing the lapping plate or lapping film in motion to remove a selected portion of the substrate to expose the transducer elements.

15. (Currently Amended) A method of fabricating a magnetic head cluster in accordance with claim 14, further comprising the step lapping wherein the at least one surface of the substrate is an edge portion of the magnetic head cluster.

16. (Currently Amended) A method of fabricating a magnetic head cluster in accordance with claim [[15]] 14, further comprising the step of measuring [[the]] resistance of the at least one of the plurality of resistive elements.

17. (Currently Amended) A method of fabricating a magnetic head cluster in accordance with claim 16, wherein the step of measuring [[the]] resistance is performed during the step of lapping, and wherein the step of lapping is performed until the resistance of at least one of the plurality of resistive element[[s]] reaches a specified resistance.

18. (Currently Amended) A method of fabricating a magnetic head cluster in accordance with claim [[15]] 14, ~~further comprising a plurality of resistive elements, and~~ wherein each of the plurality of resistive elements is formed on the surface of the substrate between two of the at least two transducer elements.

19. (Currently Amended) A method of fabricating a magnetic head cluster in accordance with claim 18, further comprising the step of measuring [[the]] resistance of at least one of the plurality of resistive elements.

20. (Currently Amended) A method of fabricating a magnetic head cluster in accordance with claim 19, wherein the step of measuring the resistance is performed during the step of lapping, and wherein the step of lapping is performed until the resistance of at least one of the plurality of resistive elements reaches a predetermined resistance.

21. (Original) A method of fabricating a magnetic head cluster in accordance with claim 15, wherein at least one of the plurality of resistive elements is selected from a group consisting of analog switch lapping guides and digital switch lapping guides.

22. (New) A method of fabricating a magnetic head cluster in accordance with claim 14 wherein the step of applying pressure is performed using a plurality of pressure application devices with plate lapping or using tension with diamond film lapping.

23 (New) A method of fabricating a magnetic head cluster in accordance with claim 14 wherein the step of lapping includes the step of introducing a diamond slurry to the surface of the lapping plate or applying a lubricant on the surface of diamond lapping film.